ABSTRACT

A surface acoustic wave device used in, for example, a mobile communications field as a filter or duplexer and the like to handle high frequencies of about several GHz is fabricated by flip-chip-connecting a surface of a piezoelectric substrate to a base board facing thereto, emitting particulate first sealing material from above a back face of the piezoelectric substrate to apply the first sealing material to the back face of the piezoelectric substrate and hang the first sealing material from edges of the piezoelectric substrate to the base board to form bridging, and forming second sealing material on the first sealing material. These operations provide a manufacturing method of a small-sized surface-mounting surface acoustic wave device appropriate for flip-chip connection.



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